AiT Semiconductor Inc.

DESCRIPTION

The S3AC_S3MC are available in SMC package.

FEATURE

- For Surface Mounted Applications
- Low Profile Package
- Glass Passivated Chip Junction
- Compliant with EU RoHS 2011/65/EU Directives

MECHANICAL DATA

- Case: SMC
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.22g / 0.0077oz

PIN DESCRIPTION



ORDERING INFORMATION

Package Type	Part Number			
SMC	S3AC			
	S3BC			
	S3DC			
	S3GC S3JC			
			S3KC	
	S3MC			
	Note	SPQ: 3,000pcs/Reel		
AiT provides all RoHS Compliant Products				

PIN#	DESCRIPTION			
1	CATHODE			
2	ANODE			



ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter		Symbol	S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	Unit
Maximum Repetitive Peak Reve	erse	V	50	100	200	400	600	900	1000	V
Voltage		V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage		VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Re	ctified					<u> </u>				
Current		IF(AV)	3							A
Peak Forward Surge Current 8.	3ms									
Single Half Sine Wave Superimposed on Rated Load		IFSM	90							A
Maximum Instantaneous Forward Voltage at 3A			1.0							V
		VF								
Maximum DC Reverse Current	T _A = 25°C		5						μA	
at Rated DC Blocking Voltage	T _A =125°C	I _R	100							
Typical Junction Capacitance ⁽¹⁾		Cj				40				pF
Typical Thermal Resistance ⁽²⁾		Reja	40						°C/W	
		Rejc	16							
Operating Temperature Range	erating Temperature Range T _j		-55 ~ +150						°C	
Storage Temperature Range		T _{stg}			-5	5~+15	50			°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(1)Measured at 1 MHz and applied reverse voltage of 4 V DC

(2)P.C.B mounted with 2.0" X 2.0" (5 X 5cm) copper pd areas.



TYPICAL PERFORMANCE CHARACTERISTICS

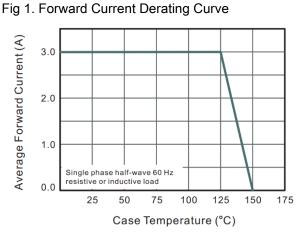
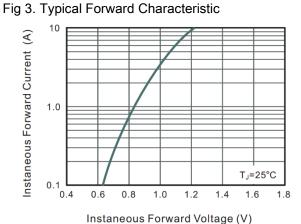


Fig. 2. Typical Farward Characteristic





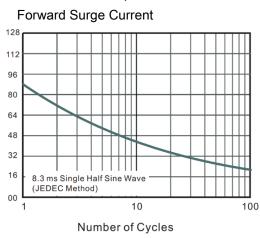


Fig 2. Typical Reverse Characteristics

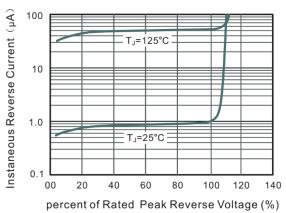
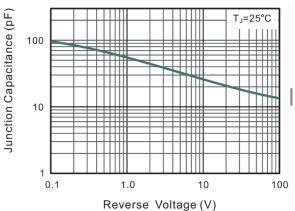


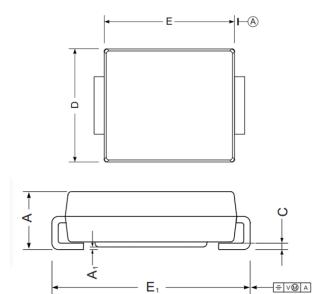
Fig 4. Typical Junction Capacitance

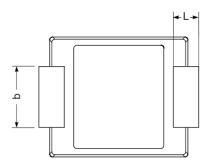




PACKAGE INFORMATION

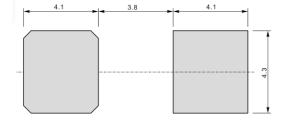
Dimension in SMC Package (Unit: mm) Plastic surface mounted package; 2 leads





SYMBOL	MIN	MAX			
A	2.000	2.620			
A1	0.210	0.310			
b	2.750	3.250			
С	0.150	0.310			
D	5.600	6.200			
E	6.500	7.000			
E1	7.600	8.000			
L	0.900	1.600			

The recommended mounting pad size



Unit : mm



IMPORTANT NOTICE

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